



## Material Content Data Sheet



<b>Sales Product Name</b>		BGA 713N7 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001067824						
<b>Package</b>		PG-TSNP-7-1		<b>Weight*</b>		3.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.114	2.97	2.97	29710	29710
leadframe	non noble metal	zinc	7440-66-6	0.004	0.11		1117	
	non noble metal	tin	7440-31-5	0.005	0.14		1396	
	non noble metal	chromium	7440-47-3	0.006	0.17		1675	
wire	non noble metal	copper	7440-50-8	2.136	55.42	55.84	554220	558408
	noble metal	gold	7440-57-5	0.042	1.10	1.10	10960	10960
	encapsulation	organic material	carbon black	1333-86-4	0.006	0.16		1641
	plastics	epoxy resin	-	0.183	4.76		47587	
		inorganic material	silicondioxide	60676-86-0	1.075	27.90	32.82	278957
leadfinish	non noble metal	tin	7440-31-5	0.111	2.89	2.89	28926	28926
plating	noble metal	silver	7440-22-4	0.104	2.69	2.69	26924	26924
glue	plastics	epoxy resin	-	0.013	0.34		3378	
		noble metal	silver	7440-22-4	0.052	1.35	1.69	13509
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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